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INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	UNKNOWN 10/666,432
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				Group Art Unit	UNKNOWN 1742
				Examiner Name	UNKNOWN Leader
Sheet	1	of	1	Attorney Docket Number	004.0108

OTHER ART

(Including Author, Title, Date, Pertinent Pages, Etc.)

WL		"Electrodeposition of Copper Thin Film on Ruthenium - A Potential Diffusion Barrier for CU Interconnects", Oliver Chyan et al., Journal of The Electrochemical Society, Volume 150, Number 5 (2003)
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WL		"Liner Materials for Direct Electrodeposition of Cu", M.W.Lane et al., Applied Physics Letter, Volume 83, Number 12, September 22, 2003
WL		"International Technology Roadmap for Semiconductors", 2001

William Leader 4/18/2007